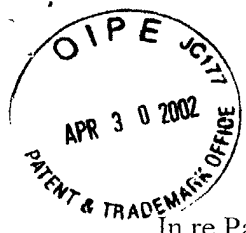


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IR-1881 (2-2532)

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5.9.02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Bharat Shivkumar et al. ✓

Date: April 22, 2002

Serial No.: 09/812,027 ✓

Group Art Unit: 2827

Filed: March 19, 2001

Examiner: J.M. Mitchell

For: SEMICONDUCTOR MULTICHIP MODULE PACKAGE WITH IMPROVED  
THERMAL PERFORMANCE, REDUCED SIZE AND IMPROVED MOISTURE  
RESISTANCE

Asst. Commissioner for Patents  
Washington, D.C. 20231

AMENDMENT/SUBMISSION

This is a response to the Office Action mailed March 28, 2002 in the above-identified application. Reconsideration of the application is respectfully requested.

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FEE CALCULATION

Any additional fee required has been calculated as follows:

\_\_\_\_\_ If checked, "Small Entity" status is claimed.

	NO. CLAIMS AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR		EXTRA PRESENT	RATE	ADDIT. FEE
TOTAL	15	MINUS	20	* =	X	(\$9 SE or \$18)	\$
INDEP.	3	MINUS	3	** =	X	(\$42 SE or \$84)	\$
FIRST PRESENTATION OF MULTIPLE DEPENDENT CLAIM						X (\$140 SE or \$280)	\$

\* not less than 20 \*\* not less than 3 TOTAL \$

If any additional payment is required, a check which includes the calculated fee of \$ \_\_\_\_\_  
(OFGS Check No. \_\_\_\_\_) is attached.